Microchip Technology - AX2000-1FG896M Datasheet

Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	586
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax2000-1fg896m

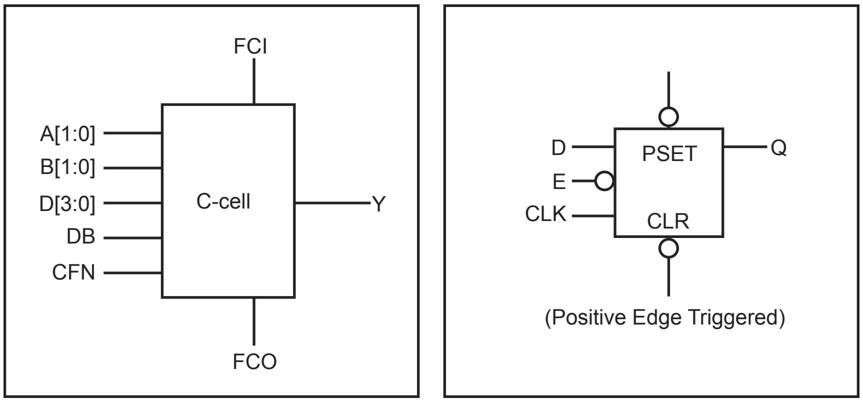
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Figure 1-2 • **Axcelerator Family Interconnect Elements**

Logic Modules

Microsemi's Axcelerator family provides two types of logic modules: the register cell (R-cell) and the combinatorial cell (C-cell). The Axcelerator device can implement more than 4,000 combinatorial functions of up to five inputs (Figure 1-3).

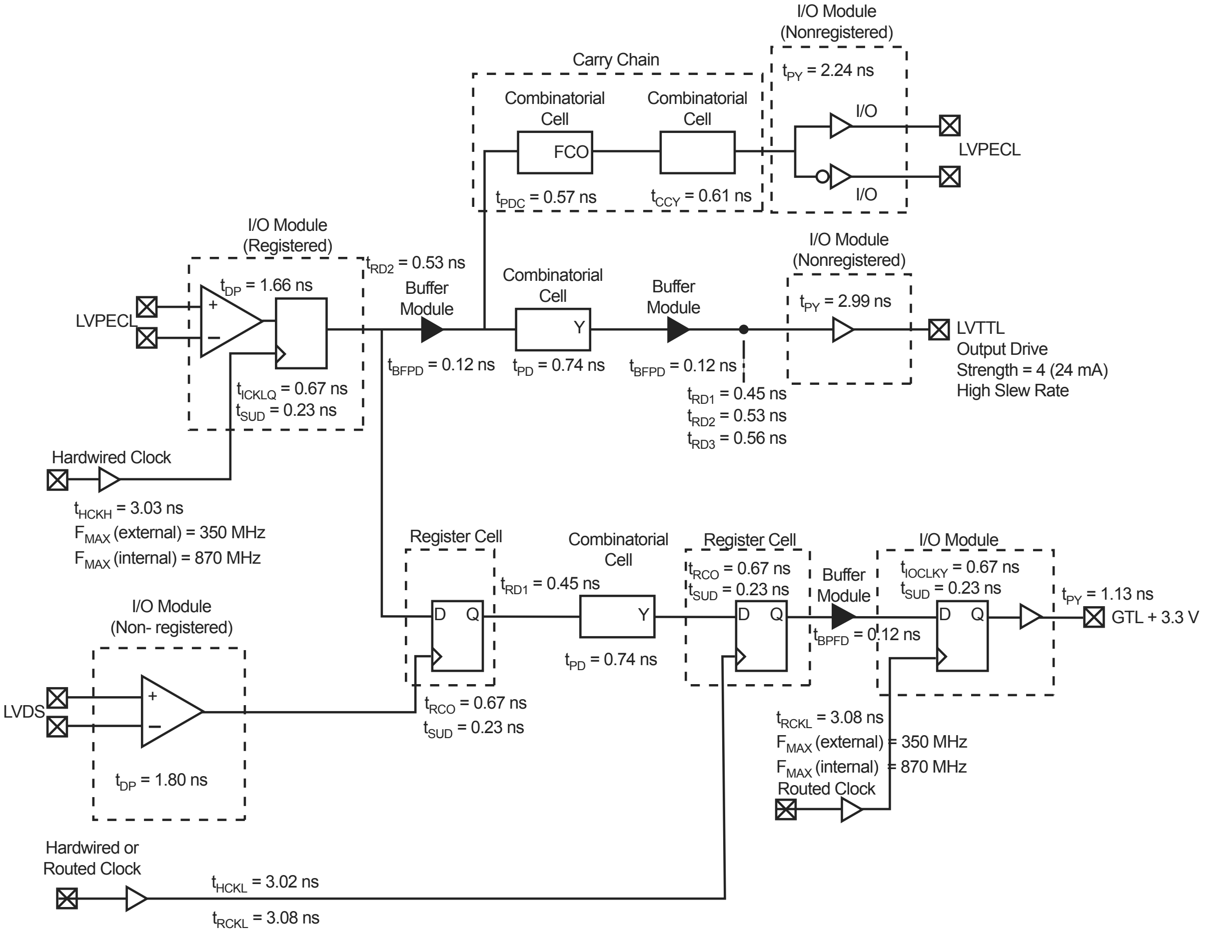


C-Cell R-Cell

Figure 1-3 • **AX C-Cell and R-Cell**

The R-cell contains a flip-flop featuring asynchronous clear, asynchronous preset, and active-low enable control signals (Figure 1-3). The R-cell registers feature programmable clock polarity selectable on a register-by-register basis. This provides additional flexibility (e.g., easy mapping of dual-data-rate functions into the FPGA) while conserving valuable clock resources. The clock source for the R-cell can be chosen from the hardwired clocks, routed clocks, or internal logic.

Timing Model



Note: Worst case timing data for the AX1000, –2 speed grade

Figure 2-1 • **Worst Case Timing Data**

Hardwired Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{HCKL}$

= (1.72 + 0.53 + 0.23) – 3.02 = –0.54 ns

Clock-to-Out (Pad-to-Pad)

$= t_{HCKL} + t_{RCO} + t_{RD1} + t_{PY}$

= 3.02 + 0.67 + 0.45 + 2.99 = 7.13 ns

Routed Clock – Using LVTTL 24 mA High Slew Clock I/O

External Setup

$= (t_{DP} + t_{RD2} + t_{SUD}) – t_{RCKH}$

= (1.72 + 0.53 + 0.23) – 3.13 = –0.65 ns

Clock-to-Out (Pad-to-Pad)

$= t_{RCKH} + t_{RCO} + t_{RD1} + t_{PY}$

= 3.13 + 0.67 + 0.45 + 3.03 = 7.24 ns

Using the Differential I/O Standards

Differential I/O macros should be instantiated in the netlist. The settings for these I/O standards cannot be changed inside Designer. Note that there are no tristated or bidirectional I/O buffers for differential standards.

Using the Voltage-Referenced I/O Standards

Using these I/O standards is similar to that of single-ended I/O standards. Their settings can be changed in Designer.

Using DDR (Double Data Rate)

In Double Data Rate mode, new data is present on every transition of the clock signal. Clock and data lines have identical bandwidth and signal integrity requirements, making it very efficient for implementing very high-speed systems.

To implement a DDR, users need to:

1. Instantiate an input buffer (with the required I/O standard)
2. Instantiate the DDR_REG macro (Figure 2-6)
3. Connect the output from the Input buffer to the input of the DDR macro

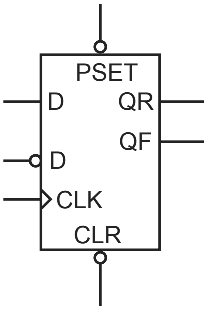


Figure 2-6 • **DDR Register**

Macros for Specific I/O Standards

There are different macro types for any I/O standard or feature that determine the required VCCI and VREF voltages for an I/O. The generic buffer macros require the LVTTL standard with slow slew rate and 24 mA-drive strength. LVTTL can support high slew rate but this should only be used for critical signals.

Most of the macro symbols represent variations of the six generic symbol types:

- CLKBUF: Clock Buffer
- HCLKBUF: Hardwired Clock Buffer
- INBUF: Input Buffer
- OUTBUF: Output Buffer
- TRIBUF: Tristate Buffer
- BIBUF: Bidirectional Buffer

Other macros include the following:

- Differential I/O standard macros: The LVDS and LVPECL macros either have a pair of differential inputs (e.g. INBUF_LVDS) or a pair of differential outputs (e.g. OUTBUF_LVPECL).
- Pull-up and pull-down variations of the INBUF, BIBUF, and TRIBUF macros. These are available only with TTL and LVCMOS thresholds. They can be used to model the behavior of the pull-up and pull-down resistors available in the architecture. Whenever an input pin is left unconnected, the output pin will either go high or low rather than unknown. This allows users to leave inputs unconnected without having the negative effect on simulation of propagating unknowns.
- DDR_REG macro. It can be connected to any I/O standard input buffers (i.e. INBUF) to implement a double data rate register. Designer software will map it to the I/O module in the same way it maps the other registers to the I/O module.

I/O Module Timing Characteristics

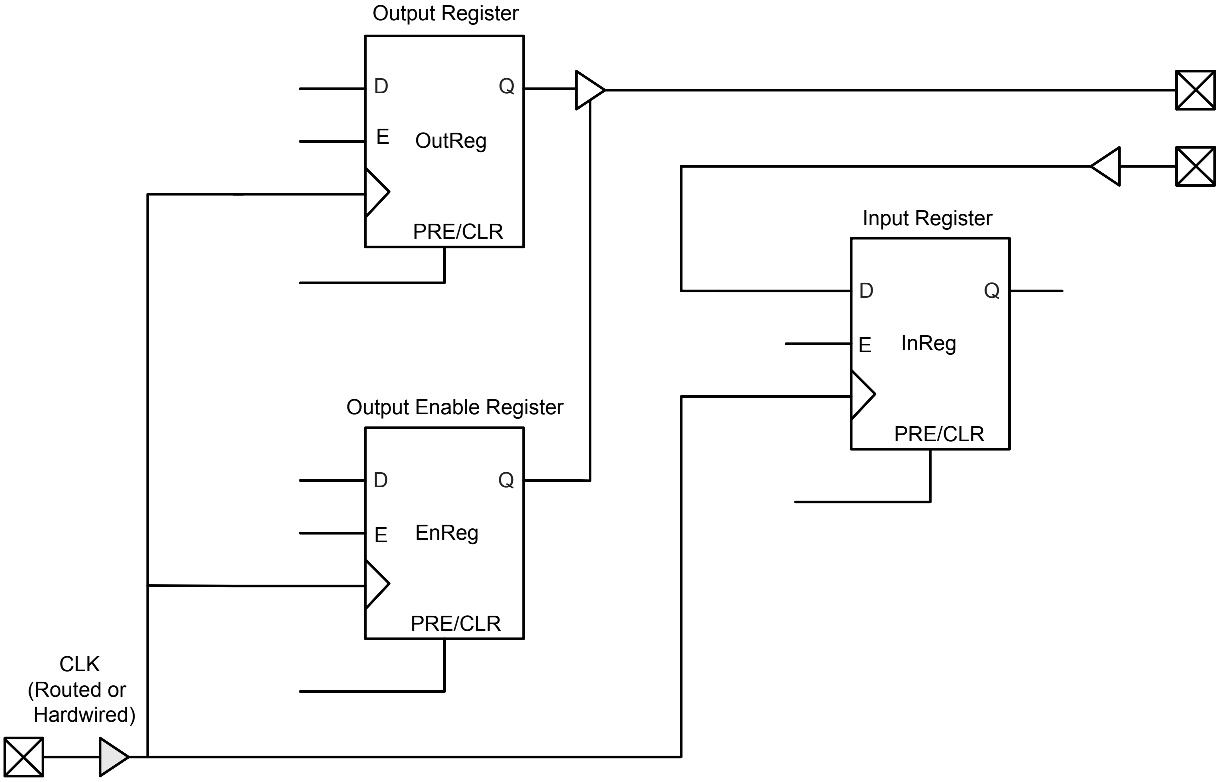


Figure 2-11 • **Timing Model**

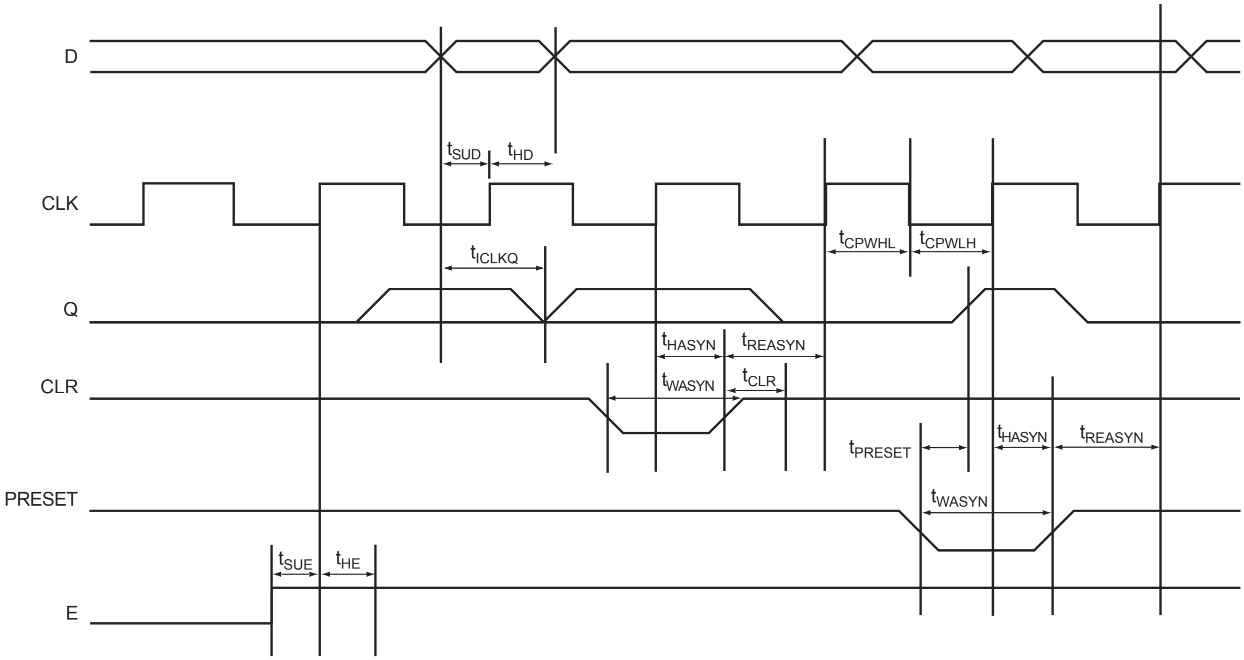


Figure 2-12 • **Input Register Timing Characteristics**

SSTL3

Stub Series Terminated Logic for 3.3 V is a general-purpose 3.3 V memory bus standard (JESD8-8). The Axcelerator devices support both classes of this standard. This requires a differential amplifier input buffer and a push-pull output buffer.

Class I

Table 2-50 • **DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
-0.3	VREF – 0.2	VREF +0.2	3.6	VREF – 0.6	VREF + 0.6	8	–8

AC Loadings

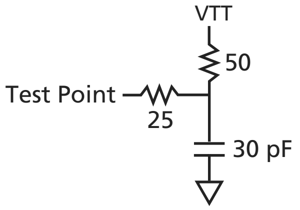


Figure 2-23 • **AC Test Loads**

Table 2-51 • **AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 1.0	VREF + 1.0	VREF	1.50	30

Note: *Measuring Point = VTRIP

Timing Characteristics

Table 2-52 • **3.3 V SSTL3 Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
3.3 V SSTL3 Class I I/O Module Timing								
t_{DP}	Input Buffer		1.78		2.03		2.39	ns
t_{PY}	Output Buffer		2.17		2.47		2.91	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Module Specifications

C-Cell

Introduction

The C-cell is one of the two logic module types in the AX architecture. It is the combinatorial logic resource in the Axcelerator device. The AX architecture implements a new combinatorial cell that is an extension of the C-cell implemented in the SX-A family. The main enhancement of the new C-cell is the addition of carry-chain logic.

The C-cell can be used in a carry-chain mode to construct arithmetic functions. If carry-chain logic is not required, it can be disabled.

The C-cell features the following (Figure 2-27):

- Eight-input MUX (data: D0-D3, select: A0, A1, B0, B1). User signals can be routed to any one of these inputs. Any of the C-cell inputs (D0-D3, A0, A1, B0, B1) can be tied to one of the four routed clocks (CLKE/F/G/H).
- Inverter (DB input) can be used to drive a complement signal of any of the inputs to the C-cell.
- A carry input and a carry output. The carry input signal of the C-cell is the carry output from the C-cell directly to the north.
- Carry connect for carry-chain logic with a signal propagation time of less than 0.1 ns.
- A hardwired connection (direct connect) to the adjacent R-cell (Register Cell) for all C-cells on the east side of a SuperCluster with a signal propagation time of less than 0.1 ns.

This layout of the C-cell (and the C-cell Cluster) enables the implementation of over 4,000 functions of up to five bits. For example, two C-cells can be used together to implement a four-input XOR function in a single cell delay.

The carry-chain configuration is handled automatically for the user with Microsemi's extensive macro library (please see the *Antifuse Macro Library Guide* for a complete listing of available Axcelerator macros).

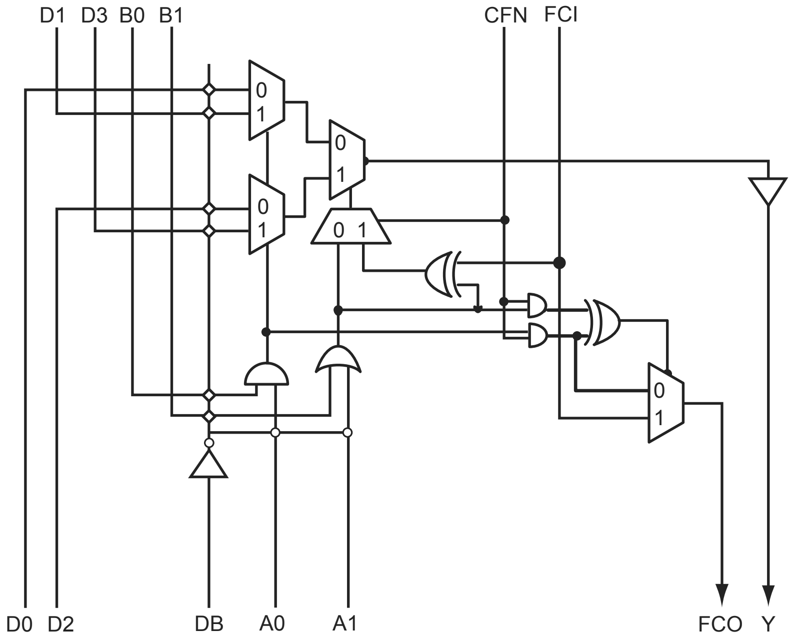


Figure 2-27 • **C-Cell**

Timing Characteristics

***Table 2-65* • AX125 Predicted Routing Delays**
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.35	0.40	0.47	ns
t_{RD2}	Routing delay for FO2	0.38	0.43	0.51	ns
t_{RD3}	Routing delay for FO3	0.43	0.48	0.57	ns
t_{RD4}	Routing delay for FO4	0.48	0.55	0.64	ns
t_{RD5}	Routing delay for FO5	0.55	0.62	0.73	ns
t_{RD6}	Routing delay for FO6	0.64	0.72	0.85	ns
t_{RD7}	Routing delay for FO7	0.79	0.89	1.05	ns
t_{RD8}	Routing delay for FO8	0.88	0.99	1.17	ns
t_{RD16}	Routing delay for FO16	1.49	1.69	1.99	ns
t_{RD32}	Routing delay for FO32	2.32	2.63	3.10	ns

***Table 2-66* • AX250 Predicted Routing Delays**
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		–2 Speed	–1 Speed	Std Speed	
Parameter	**Description**	**Typical**	**Typical**	**Typical**	**Units**
Predicted Routing Delays					
t_{DC}	DirectConnect Routing Delay, FO1	0.11	0.12	0.15	ns
t_{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t_{RD1}	Routing delay for FO1	0.39	0.45	0.53	ns
t_{RD2}	Routing delay for FO2	0.41	0.46	0.54	ns
t_{RD3}	Routing delay for FO3	0.48	0.55	0.64	ns
t_{RD4}	Routing delay for FO4	0.56	0.63	0.75	ns
t_{RD5}	Routing delay for FO5	0.60	0.68	0.80	ns
t_{RD6}	Routing delay for FO6	0.84	0.96	1.13	ns
t_{RD7}	Routing delay for FO7	0.90	1.02	1.20	ns
t_{RD8}	Routing delay for FO8	1.00	1.13	1.33	ns
t_{RD16}	Routing delay for FO16	2.17	2.46	2.89	ns
t_{RD32}	Routing delay for FO32	3.55	4.03	4.74	ns

Table 2-93 • Sixteen RAM Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		16.54		18.84		22.15	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	13.40		13.40		13.40		ns
t_{WCKP}	WCLK Minimum Period	14.15		14.15		14.15		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		18.13		20.65		24.27	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		12.83		14.62		17.18	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	14.41		14.41		14.41		ns
t_{RCKP}	RCLK Minimum Period	15.14		15.14		15.14		ns

Note: Timing data for these sixteen cascaded RAM blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.

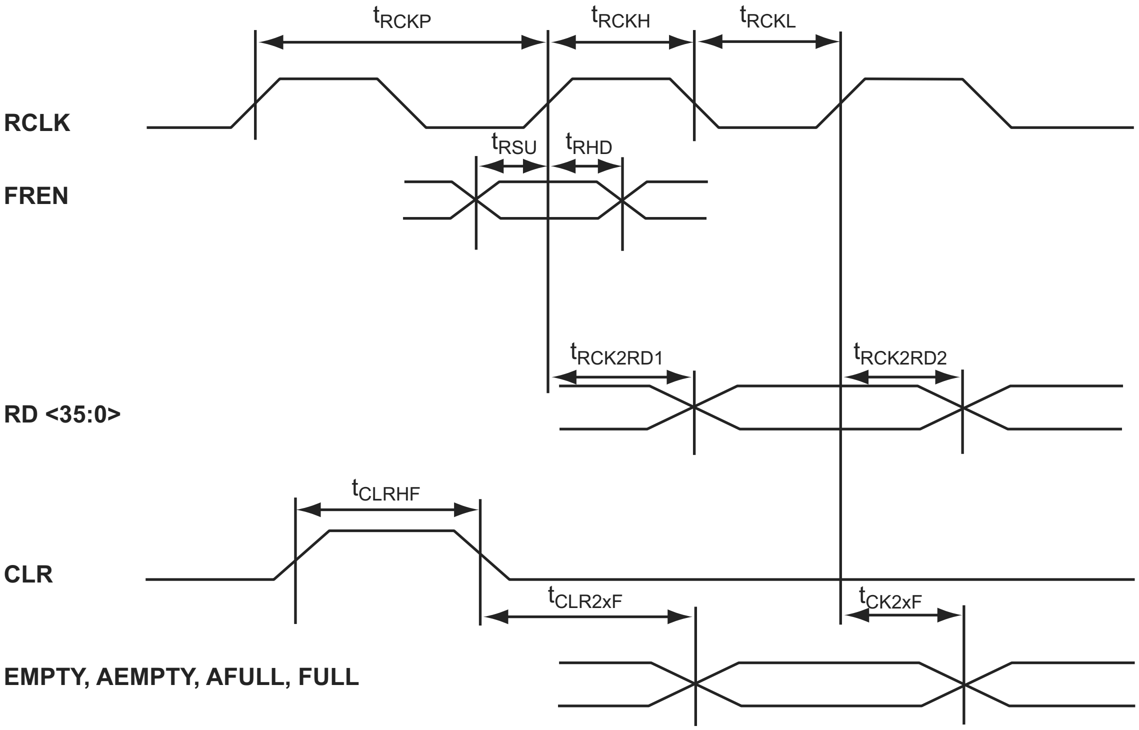


***Figure 2-68* • FIFO Read Timing**

BG729	
AX1000 Function	**Pin Number**
IO109NB3F10	V24
IO109PB3F10	V25
IO110NB3F10	T20
IO110PB3F10	T21
IO111NB3F10	W26
IO111PB3F10	W27
IO112NB3F10	U22
IO112PB3F10	U23
IO113NB3F10	Y26
IO113PB3F10	Y27
IO114NB3F10	U20
IO114PB3F10	U21
IO115NB3F10	W24
IO115PB3F10	W25
IO116NB3F10	V22
IO116PB3F10	V23
IO117NB3F10	Y24
IO117PB3F10	Y25
IO118NB3F11	V20
IO118PB3F11	V21
IO119NB3F11	AA26
IO119PB3F11	AA27
IO120NB3F11	W22
IO120PB3F11	W23
IO121NB3F11	AA24
IO121PB3F11	AA25
IO122NB3F11	W20
IO122PB3F11	W21
IO123NB3F11	AB26
IO123PB3F11	AB27
IO124NB3F11	Y22
IO124PB3F11	Y23
IO125NB3F11	AB24
IO125PB3F11	AB25
IO126NB3F11	AA22
IO126PB3F11	AA23
IO127NB3F11	AC26

BG729	
AX1000 Function	**Pin Number**
IO127PB3F11	AC27
IO128NB3F11	Y20
IO128PB3F11	W19
Bank 4	
IO129NB4F12	AA20
IO129PB4F12	Y21
IO130NB4F12	AB22
IO130PB4F12	AB23
IO131NB4F12	AC22
IO131PB4F12	AC23
IO132NB4F12	AD23
IO132PB4F12	AD24
IO133NB4F12	AF23
IO133PB4F12	AE23
IO134NB4F12	AC21
IO134PB4F12	AB21
IO135NB4F12	AC20
IO135PB4F12	AB20
IO136NB4F12	AD21
IO136PB4F12	AD22
IO137NB4F12	Y19
IO137PB4F12	AA19
IO138NB4F12	AE21
IO138PB4F12	AE22
IO139NB4F13	AF21
IO139PB4F13	AF22
IO140NB4F13	AG22
IO140PB4F13	AG23
IO141NB4F13	Y18
IO141PB4F13	AA18
IO142NB4F13	AE20
IO142PB4F13	AD20
IO143NB4F13	AG20
IO143PB4F13	AG21
IO144NB4F13	AC19
IO144PB4F13	AB19
IO145NB4F13	AD18

BG729	
AX1000 Function	**Pin Number**
IO145PB4F13	AD19
IO146NB4F13	AC18
IO146PB4F13	AB18
IO147NB4F13	Y17
IO147PB4F13	AA17
IO148NB4F13	AF19
IO148PB4F13	AF20
IO149NB4F13	AC17
IO149PB4F13	AB17
IO150NB4F13	AE18
IO150PB4F13	AE19
IO151NB4F13	AA16
IO151PB4F13	Y16
IO152NB4F14	AG18
IO152PB4F14	AG19
IO153NB4F14	AC16
IO153PB4F14	AB16
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AB15
IO155PB4F14	AC15
IO156NB4F14	AE16
IO156PB4F14	AE17
IO157NB4F14	Y15
IO157PB4F14	AA15
IO158NB4F14	AG16
IO158PB4F14	AG17
IO159NB4F14/CLKEN	AF15
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AD14
IO160PB4F14/CLKFP	AD15
Bank 5	
IO161NB5F15/CLKGN	AE14
IO161PB5F15/CLKGP	AE15
IO162NB5F15/CLKHN	AC13
IO162PB5F15/CLKHP	AD13
IO163NB5F15	Y14

BG729	
AX1000 Function	Pin Number
VCCIB0	B4
VCCIB0	C4
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K12
VCCIB0	K13
VCCIB1	A24
VCCIB1	B24
VCCIB1	C24
VCCIB1	J16
VCCIB1	J17
VCCIB1	J18
VCCIB1	K15
VCCIB1	K16
VCCIB2	D25
VCCIB2	D26
VCCIB2	D27
VCCIB2	K19
VCCIB2	L19
VCCIB2	M18
VCCIB2	M19
VCCIB2	N18
VCCIB3	AD25
VCCIB3	AD26
VCCIB3	AD27
VCCIB3	R18
VCCIB3	T18
VCCIB3	T19
VCCIB3	U19
VCCIB3	V19
VCCIB4	AE24
VCCIB4	AF24
VCCIB4	AG24
VCCIB4	V15
VCCIB4	V16
VCCIB4	W16

BG729	
AX1000 Function	Pin Number
VCCIB4	W17
VCCIB4	W18
VCCIB5	AE4
VCCIB5	AF4
VCCIB5	AG4
VCCIB5	V12
VCCIB5	V13
VCCIB5	W10
VCCIB5	W11
VCCIB5	W12
VCCIB6	AD1
VCCIB6	AD2
VCCIB6	AD3
VCCIB6	R10
VCCIB6	T10
VCCIB6	T9
VCCIB6	U9
VCCIB6	V9
VCCIB7	D1
VCCIB7	D2
VCCIB7	D3
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCOMPLA	B13
VCOMPLB	A14
VCOMPLC	A15
VCOMPLD	J15
VCOMPLE	AG15
VCOMPLF	W15
VCOMPLG	AC14
VCOMPLH	W13
VPUMP	D24

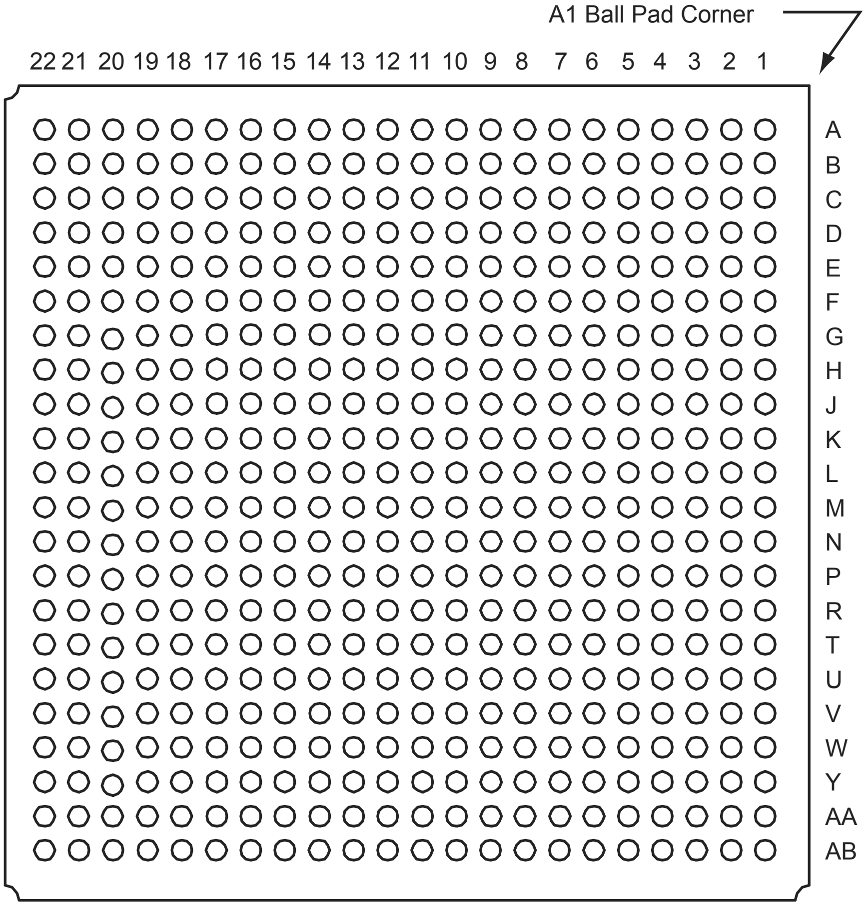
FG256-Pin FBGA	
AX125 Function	**Pin Number**
VCCA	L10
VCCA	L7
VCCA	L8
VCCA	L9
VCCA	N3
VCCA	P14
VCCPLA	C7
VCCPLB	D6
VCCPLC	A10
VCCPLD	D10
VCCPLE	P10
VCCPLF	N11
VCCPLG	T7
VCCPLH	N7
VCCDA	A2
VCCDA	C13
VCCDA	D9
V_{CCDA}	H1
VCCDA	J15
VCCDA	N14
VCCDA	N8
VCCDA	P4
VCCIB0	E6
VCCIB0	E7
VCCIB0	E8
VCCIB1	E10
VCCIB1	E11
VCCIB1	E9
VCCIB2	F12
VCCIB2	G12
VCCIB2	H12
VCCIB3	J12
VCCIB3	K12
VCCIB3	L12
VCCIB4	M10
VCCIB4	M11
VCCIB4	M9
VCCIB5	M6
VCCIB5	M7
VCCIB5	M8
VCCIB6	J5
VCCIB6	K5
VCCIB6	L5
VCCIB7	F5
VCCIB7	G5
VCCIB7	H5
VCOMPLA	A7
VCOMPLB	D7
VCOMPLC	B9
VCOMPLD	D11
VCOMPLE	T10
VCOMPLF	N10
VCOMPLG	R8
VCOMPLH	N6
VPUMP	A14

FG324	
AX125 Function	**Pin Number**
GND	R4
GND	T16
GND	T3
GND	U17
GND	U2
GND	V1
GND	V18
GND/LP	E5
NC	A10
NC	A11
NC	A12
NC	A13
NC	A8
NC	A9
NC	B12
NC	F15
NC	F4
NC	G15
NC	G4
NC	H14
NC	H15
NC	H5
NC	J1
NC	J14
NC	J15
NC	J5
NC	K14
NC	K15
NC	K5
NC	L14
NC	L15
NC	L5
NC	M4
NC	M5
NC	N17

FG324	
AX125 Function	**Pin Number**
NC	N4
NC	N5
NC	R12
NC	R13
NC	R6
NC	R7
NC	T12
NC	T6
NC	U16
NC	V17
PRA	E9
PRB	D9
PRC	P10
PRD	R10
TCK	E6
TDI	D7
TDO	D5
TMS	D4
TRST	D6
VCCA	E15
VCCA	G10
VCCA	G11
VCCA	G5
VCCA	G8
VCCA	G9
VCCA	H12
VCCA	H7
VCCA	J12
VCCA	J7
VCCA	K12
VCCA	K7
VCCA	L12
VCCA	L7
VCCA	M10
VCCA	M11

FG324	
AX125 Function	**Pin Number**
VCCA	M8
VCCA	M9
VCCA	P4
VCCA	R15
VCCPLA	D8
VCCPLB	E7
VCCPLC	B11
VCCPLD	E11
VCCPLE	R11
VCCPLF	P12
VCCPLG	U8
VCCPLH	P8
VCCDA	B3
VCCDA	D14
VCCDA	E10
VCCDA	J2
VCCDA	K16
VCCDA	P15
VCCDA	P9
VCCDA	R5
VCCIB0	F7
VCCIB0	F8
VCCIB0	F9
VCCIB1	F10
VCCIB1	F11
VCCIB1	F12
VCCIB2	G13
VCCIB2	H13
VCCIB2	J13
VCCIB3	K13
VCCIB3	L13
VCCIB3	M13
VCCIB4	N10
VCCIB4	N11
VCCIB4	N12

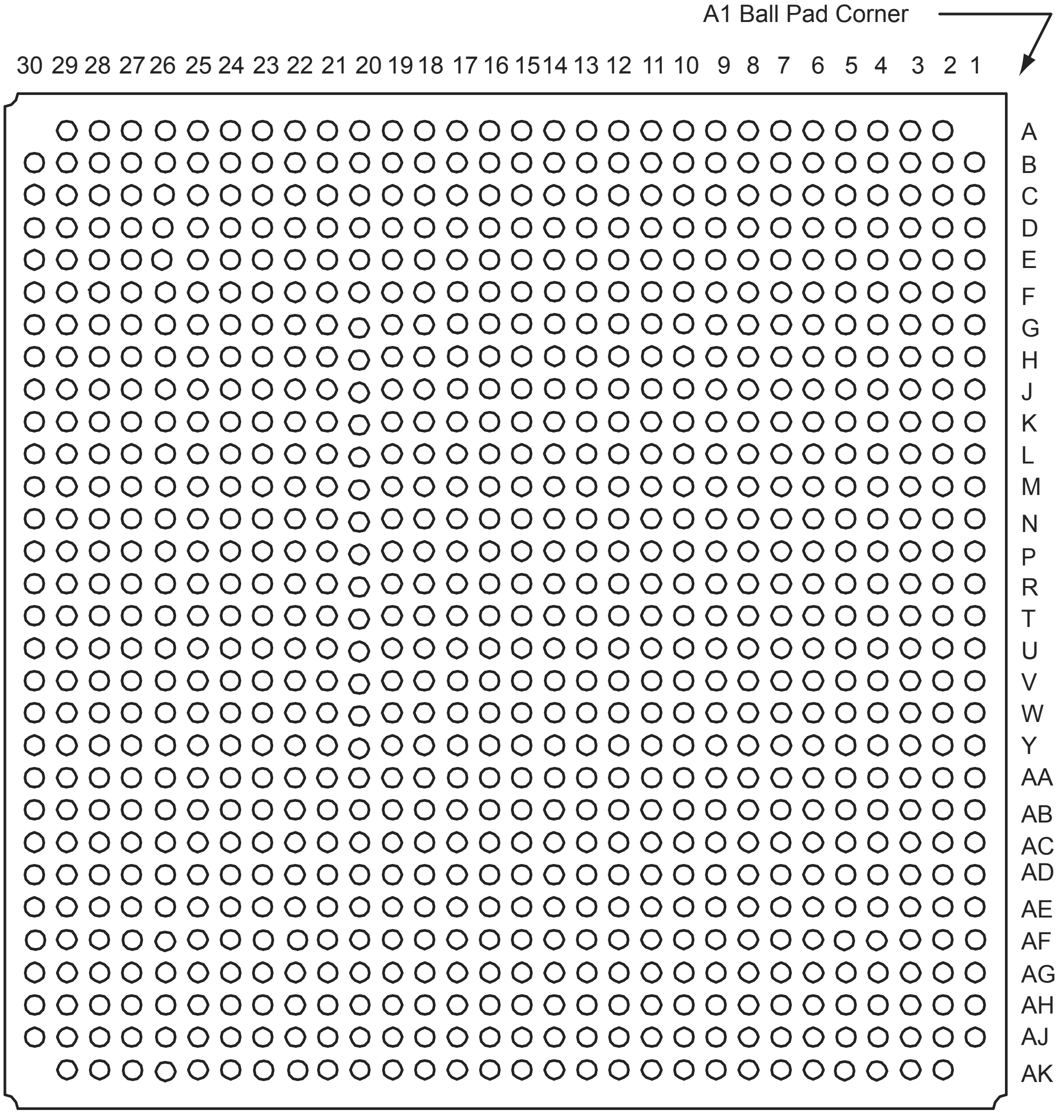
FG484



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

CQ352	
AX250 Function	**Pin Number**
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX250 Function	**Pin Number**
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CQ352	
AX500 Function	**Pin Number**
IO87PB4F8	171
IO89NB4F8	166
IO89PB4F8	167
IO94NB4F9	164
IO94PB4F9	165
IO95NB4F9	160
IO95PB4F9	161
IO97NB4F9	158
IO97PB4F9	159
IO99NB4F9	154
IO99PB4F9	155
IO100NB4F9	146
IO100PB4F9	147
IO101NB4F9	152
IO101PB4F9	153
IO103NB4F9/CLKEN	142
IO103PB4F9/CLKEP	143
IO104NB4F9/CLKFN	136
IO104PB4F9/CLKFP	137
Bank 5	
IO105NB5F10/CLKGN	128
IO105PB5F10/CLKGP	129
IO106NB5F10/CLKHN	122
IO106PB5F10/CLKHP	123
IO107NB5F10	118
IO107PB5F10	119
IO114NB5F11	112
IO114PB5F11	113
IO115NB5F11	110
IO115PB5F11	111
IO116NB5F11	106
IO116PB5F11	107
IO117NB5F11	104
IO117PB5F11	105
IO119NB5F11	100

CQ352	
AX500 Function	**Pin Number**
IO119PB5F11	101
IO121NB5F11	98
IO121PB5F11	99
IO123NB5F11	94
IO123PB5F11	95
IO125NB5F11	92
IO125PB5F11	93
Bank 6	
IO126PB6F12	86
IO127NB6F12	84
IO127PB6F12	85
IO129NB6F12	82
IO129PB6F12	83
IO131NB6F12	78
IO131PB6F12	79
IO133NB6F12	76
IO133PB6F12	77
IO134NB6F12	72
IO134PB6F12	73
IO135NB6F12	70
IO135PB6F12	71
IO137NB6F13	66
IO137PB6F13	67
IO138NB6F13	64
IO138PB6F13	65
IO139NB6F13	60
IO139PB6F13	61
IO141NB6F13	54
IO141PB6F13	55
IO142NB6F13	58
IO142PB6F13	59
IO143NB6F13	52
IO143PB6F13	53
IO145NB6F13	48
IO145PB6F13	49

CQ352	
AX500 Function	**Pin Number**
IO146NB6F13	46
IO146PB6F13	47
Bank 7	
IO147NB7F14	40
IO147PB7F14	41
IO148NB7F14	42
IO148PB7F14	43
IO149NB7F14	36
IO149PB7F14	37
IO151NB7F14	30
IO151PB7F14	31
IO152NB7F14	34
IO152PB7F14	35
IO153NB7F14	28
IO153PB7F14	29
IO155NB7F14	24
IO155PB7F14	25
IO157NB7F14	22
IO157PB7F14	23
IO159NB7F15	16
IO159PB7F15	17
IO160NB7F15	18
IO160PB7F15	19
IO161NB7F15	12
IO161PB7F15	13
IO163NB7F15	10
IO163PB7F15	11
IO165NB7F15	6
IO165PB7F15	7
IO167NB7F15	4
IO167PB7F15	5
Dedicated I/O	
GND	1
GND	9
GND	15

4 – Datasheet Information

List of Changes

The following table lists critical changes that were made in the current version of the document.

Revision	Changes	Page
Revision 18 (March 2012)	Table 2-1 • Absolute Maximum Ratings was updated to correct the maximum DC core supply voltage (VCCA) from 1.6 V to 1.7 V (SAR 36786). The maximum input voltage (VI) was corrected from 3.75 V to 4.1 V (SAR 35419).	2-1
	Values for tristate leakage current IOZ, and IIH and IIL were added to Table 2-3 • Standby Current (SARs 35774, 32021).	2-2
	Figure 2-2 • VCCPLX and VCOMPLX Power Supply Connect was updated to correct the units for the resistance from "W" to Ω (SAR 36415).	2-9
	In the Introduction to the "User I/Os" section, the following sentence was added to clarify the slew rate setting (SAR 34943): The slew rate setting is effective for both rising and falling edges.	2-11
	Figure 2-3 • Use of an External Resistor for 5 V Tolerance was revised to show the VCCI and GND clamp diodes. The explanatory text above the figure was revised as well (SAR 34942).	2-13
	EQ 3 for 5 V tolerance was corrected to change Vdiode from 0.6 V to 0.7 V (SAR 36786).	2-13
	Additional information was added to the "Using the Weak Pull-Up and Pull-Down Circuits" section to clarify how the weak pull-up and pull-down resistors are physically implemented (SAR 34945).	2-17
	The description for the C_{INCLK} parameter in Table 2-18 • Input Capacitance was changed from "Input capacitance on clock pin" to "Input capacitance on HCLK and RCLK pin" (SAR 34944).	2-21
	Table 2-19 • I/O Input Rise Time and Fall Time* is new (SAR 34942).	2-21
	The minimum VIL for 1.5 V LVCMOS and PCI was corrected from –0.5 to –0.3 in Table 2-29 • DC Input and Output Levels and Table 2-33 • DC Input and Output Levels (SAR 34358).	2-38, 2-40
	Support for simulating the GCLR/ GPSET feature in the Axcelerator Family was added in Libero software v9.0 SPI1. Reference to the section explaining this in the *Antifuse Macro Library Guide* was added to the "R-Cell" section (SAR 26413).	2-58
	The enable signal in Figure 2-32 • R-Cell Delays was corrected to show it is active low rather than active high (SAR 34946).	2-59
Revision 17 (September 2011)	The versioning system for datasheets has been changed. Datasheets are assigned a revision number that increments each time the datasheet is revised. The "Axcelerator Family Device Status" table indicates the status for each device in the device family.	iii
	The "Features" section, "Programmable Interconnect Element" section, and "Security" section were revised to clarify that although no existing security measures can give an absolute guarantee, Microsemi FPGAs implement the best security available in the industry (SAR 32865).	i, 1-1, 2-108

Revision	Changes	Page
Revision 17 (continued)	The C180 package was removed from product tables and the "Package Pin Assignments" section (PDN 0909).	3-1
	Package names used in the"Axcelerator Family Product Profile" and "Package Pin Assignments" section were revised to match standards given in *Package Mechanical Drawings* (SAR 27395).	i, 3-1
	The "Introduction" section for "User I/Os" was updated as follows: "The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os" (SARs 24181, 24309).	2-11
	Power values in Table 2-4 • Default CLOAD/VCCI were updated to reflect those of SmartPower (SAR 33945).	2-3
	Two parameter names were corrected in Figure 2-10 • Output Buffer Delays. One occurrence of t_{ENLZ} was changed to t_{ENZL} and one occurrence of t_{ENHZ} was changed to t_{ENZH} (SAR 33890).	2-22
	The "Timing Model" section was updated with new timing values. Timing tables in the "I/O Specifications" section were updated to include enable paths. Values in the timing tables in the "Voltage-Referenced I/O Standards" section and "Differential Standards" section were updated. Table 2-63 • R-Cell was updated (SAR 33945).	2-8, 2-26 to 2-53
	Figure 2-11 • Timing Model was replaced (SAR 33043).	2-23
	The timing tables for "RAM" and "FIFO" were updated (SAR 33945).	2-90 to 2-106
	"Data Registers (DRs)" values were modified for IDCODE and USERCODE (SARs 18257, 26406).	2-108
	The package diagram for the "CQ208" package was incorrect and has been replaced with the correct diagram (SARs 23865, 26345).	3-89
Revision 16 (v2.8, Oct. 2009)	The datasheet was updated to include AX2000-CQ2526 information.	N/A
	MIL-STD-883 Class B is no longer supported by Axcelerator FPGAs and as a result was removed.	N/A
	A footnote was added to the "Introduction" in the "Axcelerator Clock Management System" section.	2-75
Revision 15 (v2.7, Nov. 2008)	RoHS-compliant information was added to the "Ordering Information".	ii
	ACTgen was changed to SmartGen because ACTgen is obsolete.	N/A
Revision 14 (v2.6)	In Table 2-4, the units for the P_{LOAD}, P_{10}, and $P_{I/O}$ were updated from mW/MHz to mW/MHz.	2-3
	In the "Pin Descriptions"section, the HCLK and CLK descriptions were updated to include tie-off information.	2-9
	The "Global Resource Distribution" section was updated.	2-70
	The " CG624" table was updated.	3-116
Revision 13 (v2.5)	A note was added to Table 2-2.	2-1
	In the "Package Thermal Characteristics", the temperature was changed from 150°C to 125°C.	2-6

Revision	Changes	Page
Revision 3 (continued)	The timing characteristics tables from pages 2-26 to 2-60 were updated.	2-26 to 2-60
	The "Global Resources" section was updated.	2-66
	The timing characteristics tables from pages 2-102 to 2-103 were updated.	2-102 to 2-103
	The "PQ208", "FG256", and "FG324" tables are new.	3-9,3-16, 3-84